

## 1. Summary

- RoHS Compliant & Halogen Free
- Applications: All high-density boards
- Product Features: Small surface mountable, Solid state, Faster time to trip than standard SMD devices, Lower resistance than standard SMD devices
- Operation Current: 160mA
- Maximum Voltage: 48V
- Temperature Range : -40°C to 85°C
- AEC-Q200 qualified.

## 2. Electrical Characteristics (23°C)

Part Number	Hold Current	Trip Current	Rated Voltage	Max Current	Typical Power	Max Time to Trip		Resistance	
	$I_H$ , A	$I_T$ , A	$V_{MAX}$ , VDC	$I_{MAX}$ , A	$P_d$ , W	Current	Time	$R_{MIN}$	$R_{1MAX}$
	$I_H$ , A	$I_T$ , A	$V_{MAX}$ , VDC	$I_{MAX}$ , A	$P_d$ , W	Amp	Sec	Ohms	Ohms
SMD1206P016TFQ	0.16	0.45	48	100	0.6	1.00	0.30	1.10	5.00

$I_H$ =Hold current-maximum current at which the device will not trip at 23°C still air.

$I_T$ =Trip current-minimum current at which the device will always trip at 23°C still air.

$V_{MAX}$ =Maximum voltage device can withstand without damage at it rated current.( $I_{MAX}$ )

$I_{MAX}$ = Maximum fault current device can withstand without damage at rated voltage ( $V_{MAX}$ ).

$P_d$ =Typical power dissipated-type amount of power dissipated by the device when in the tripped state in 23°C still air environment.

$R_{MIN}$ =Minimum device resistance at 23°C prior to tripping.

$R_{1MAX}$ =Maximum device resistance at 23°C measured 1 hour after tripping or reflow soldering of 260°C for 20 seconds.

Termination pad characteristics

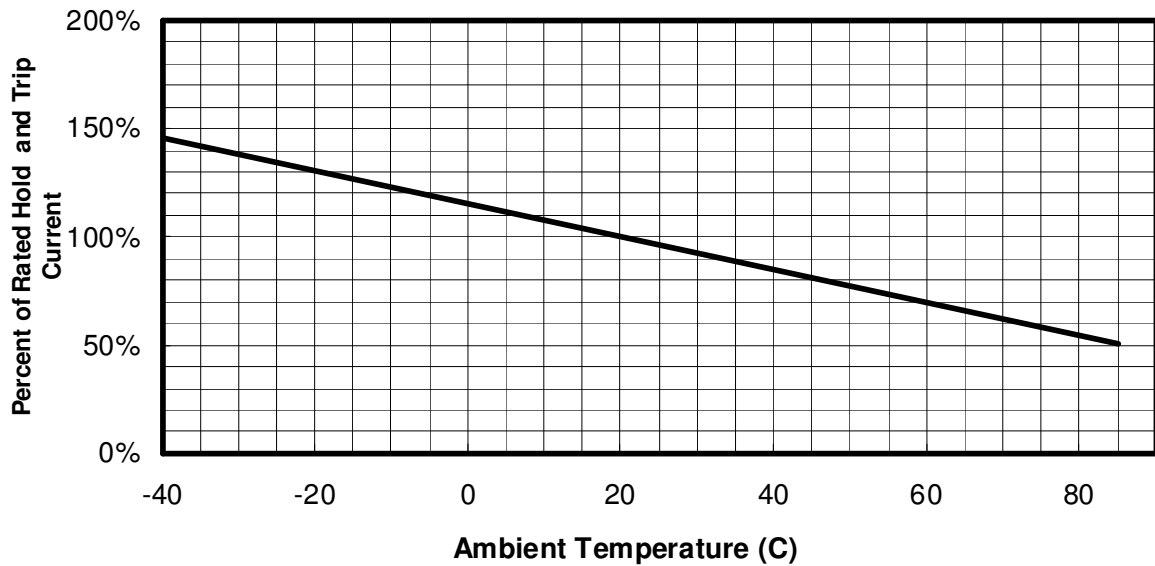
Termination pad materials: Pure Tin

## 3. FSMD Product Dimensions (Millimeters)

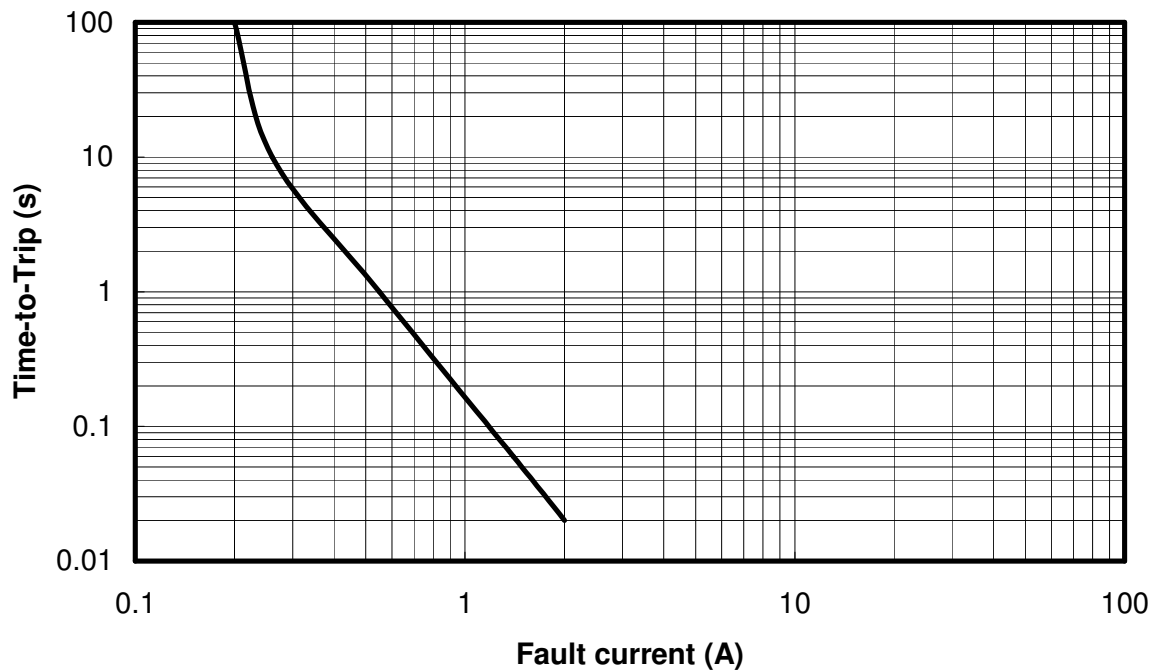


Part Number	A		B		C		D		E		Marking
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
SMD1206P016TFQ	3.00	3.50	1.50	1.80	0.45	0.75	0.10	0.75	0.10	0.45	FK

## 4. Thermal Derating Curve



## 5. Typical Time-To-Trip at 23°C



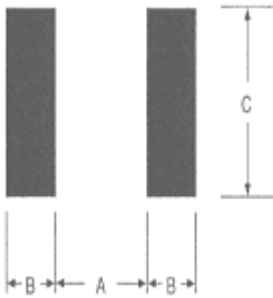
## 6. Material Specification

Terminal pad material: Pure Tin

Soldering characteristics: Meets EIA specification RS 186-9E, ANSI/J-std-002 Category 3

## 7. Pad Layouts 、 Solder Reflow and Rework Recommendations

The dimension in the table below provide the recommended pad layout for each SMD1206P016TFQ device



**Pad dimensions (millimeters)**

Device	A Nominal	B Nominal	C Nominal
SMD1206P016TFQ	2.00	1.00	1.90

Profile Feature	Pb-Free Assembly
<b>Average Ramp-Up Rate (T<sub>smax</sub> to T<sub>p</sub>)</b>	3 °C/second max.
<b>Preheat :</b>	
Temperature Min (T <sub>smin</sub> )	150 °C
Temperature Max (T <sub>smax</sub> )	200 °C
Time (t <sub>smin</sub> to t <sub>smax</sub> )	60-180 seconds
<b>Time maintained above:</b>	
Temperature(T <sub>L</sub> )	217 °C
Time (t <sub>L</sub> )	60-150 seconds
<b>Peak/Classification Temperature(T<sub>p</sub>) :</b>	260 °C
<b>Time within 5°C of actual Peak :</b>	
Temperature (t <sub>p</sub> )	20-40 seconds
<b>Ramp-Down Rate :</b>	6 °C/second max.
<b>Time 25 °C to Peak Temperature :</b>	8 minutes max.

Note 1: All temperatures refer to of the package,  
measured on the package body surface.

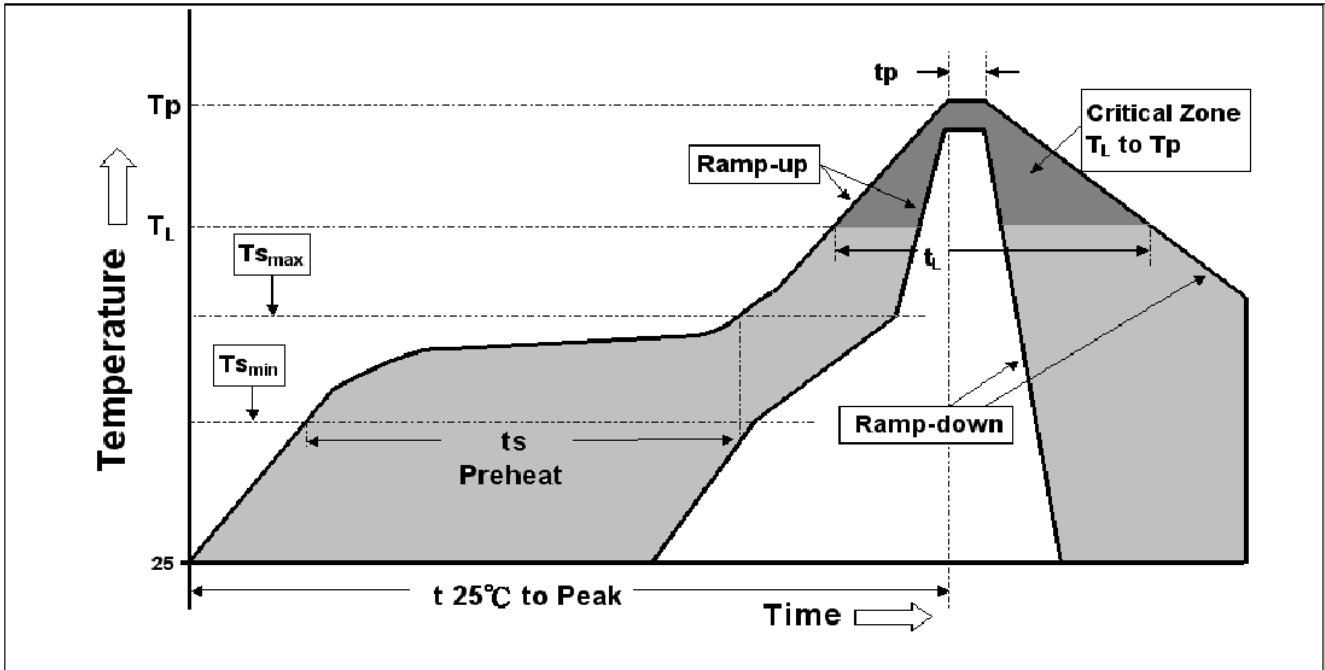
### Solder reflow

- ※ Due to “Lead Free” nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.
1. Recommended max past thickness > 0.25mm.
  2. Devices can be cleaned using standard methods and aqueous solvent.
  3. Rework use standard industry practices.
  4. Storage Environment : < 30°C / 60%RH

### **Caution:**

1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
2. Devices are not designed to be wave soldered to the bottom side of the board.

## Reflow Profile



**Warning:** -Operation beyond the specified maximum ratings or improper use may result in damage and possible electrical arcing and/or flame.



- PPTC device are intended for occasional overcurrent protection. Application for repeated overcurrent condition and/or prolonged trip are not anticipated.
- Avoid contact of PPTC device with chemical solvent. Prolonged contact will damage the device performance.

### NOTICE

Leiditech reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. Leiditech does not assume any liability arising out of the application or use of any product described herein.

Shanghai Leiditech Electronic Co.,Ltd  
 Email: sale1@leiditech.com  
 Tel : +86- 021 50828806  
 Fax : +86- 021 50477059